

Datasheet

ENGLISH

Multilayer Ceramic Common Mode Filter, Halogen Free Product,

RS Stock number 884-2234

FEATURES

- Miniature footprint: 1.25 X 1.00 X 0.8 mm³
- Multilayer LTCC (Low Temperature Ceramic Cofired) Technology
- 3. Reflow solderable SMD Devices
- 4. Wide Pass Band (Cut-Off Frequency: -3dB@3GHz Typical)
- High Attenuation for common mode noise
- 6. Special 3D layout design to minimize phase shifting

APPLICATIONS

- EMI suppression on HDMI/(mini)LVDS/DVI/SATA/PCI-E/Display Port high speed data transmission
- 2. PC related, LCD TV, PDP TV, Projector, STB, Blue-ray DVD, panel.

CONSTRUCTION

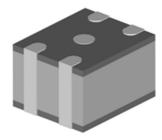




Fig 1. Outline of 1210 size Common Mode Filter and Schematics

DIMENSIONS

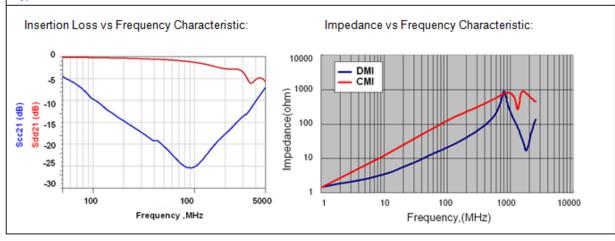
Figure	Symbol	Dimension
	L	1.25 ± 0.10mm
	W	1.00 ± 0.10mm
N V	Т	0.80 ± 0.10mm
	А	0.55 ± 0.10mm
	В	0.20 ± 0.15mm
B	С	0.30 ± 0.10mm



ELECTRICAL CHARACTERISTICS

Specification	
3 GHz (Typical)	
120 ohm ± 20% @ 100MHz	
Max. 1.2 Ω	
300 mA	
100 Ω(Typical)	
- 40 °C ~ +85 °C	

Typical Electrical Chart



SOLDER LAND PATTERN

Figure	Symbol	Dimension (mm)
L1	L1	1.75 ± 0.05
	L2	0.30 ± 0.10
	L3	0.75 ± 0.05
L3	L4	0.55 ± 0.05

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.



RELIABILITY TEST

Test item		Test condition / Test method	Specification	
Solderability JIS C 0050-4.6 JESD22-B102D		*Solder bath temperature : 235 ± 5°C *Immersion time : 2 ± 0.5 sec *Solder : Sn3Ag0.5Cu for lead-free	At least 95% of a surface of each terminal electrode must be covered by fresh solder.	
Leaching (Resistance dissolution metallization) IEC 60068-2-58	to of	*Solder bath temperature : $260 \pm 5^{\circ}$ C *Leaching immersion time : 30 ± 0.5 sec *Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.	
Resistance to solderin JIS C 0050-5.4	g heat	*Preheating temperature: 120~150 \(\), 1 minute. *Solder temperature: 270\(\) 5°C *Immersion time: 10\(\) 1 sec *Solder: Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24\(\) 2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test. Loss of metallization on the edges of each electrode shall not exceed 25%.	
Drop Test JIS C 0044		*Height: 75 cm *Test Surface: Rigid surface of concrete or steel. *Times: 6 surfaces for each units; 2 times for each side.	No mechanical damage. Samples shall satisfy electrical specification after test.	
Adhesive Strength of Termination JIS C 0051-7.4.3		*Pressurizing force : 5N(≤0603) ; 10N(>0603) *Test time : 10±1 sec	No remarkable damage or removal of the termination.	
Bending test JIS C 0051-7.4.1		The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage. Samples shall satisfy electrical specification after test.	



Temperature cycle JIS C 0025	1. 30±3 minutes at -40°C±3°C, 2. 10~15 minutes at room temperature,	No mechanical damage. Samples shall satisfy electrical
	3. 30±3 minutes at +85°C±3°C,	specification after test.
	4. 10~15 minutes at room temperature,	
	Total 100 continuous cycles Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
Vibration	*Frequency: 10Hz~55Hz~10Hz(1min)	No mechanical damage.
JIS C 0040	*Total amplitude: 1.5mm	Samples shall satisfy electrical specification after test.
	*Test times: 6hrs.(Two hrs each in three mutually perpendicular directions)	Specification after test.
High temperature	*Temperature : 85°C±2°C	No mechanical damage.
JIS C 0021	*Test duration: 1000+24/-0 hours	Samples shall satisfy electrical
	Measurement to be made after keeping at room temperature for 24±2 hrs	specification after test.
Humidity	*Humidity : 90% to 95% R.H.	No mechanical damage.
(steady conditions)	*Temperature : 40±2°C	Samples shall satisfy electrical
JIS C 0022	*Time: 1000+24/-0 hrs.	specification after test.
	Measurement to be made after keeping at room temperature for 24±2 hrs	
	*500hrs measuring the first data then	
	1000hrs data	
Low temperature	*Temperature : -40°C±2°C	No mechanical damage.
JIS C 0020	*Test duration: 1000+24/-0 hours	Samples shall satisfy electrical specification after test.
	Measurement to be made after keeping at room temperature for 24±2 hrs	Specification after test.



SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

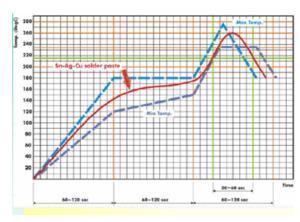


Fig 2. Infrared soldering profile

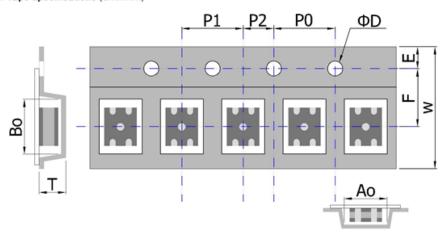
ORDERING CODE

RG	CMF	1210	121	Н	4	T
Walsin	Product Code	Dimension code	CM Impedance	Application	Specification	Packing
RG device	CMF: Common Mode Filter	1210 = Width12, Length 10,	121:120 ohm	H: HDMI/ DVI/ LVDS/ SATA/ PCI-/ D-Port	Code from 0 ~ 9 dependent on different electrical specification	T: Reeled

Minimum Ordering Quantity: 2000 pcs per reel.

PACKAGING

Paper Tape specifications (unit:mm)

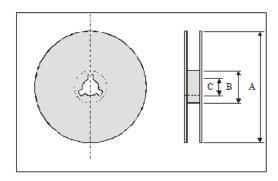


Index	Ao	Во	ΦD	Т	W
Dimension (mm)	1.20 ± 0.10	1.40 ± 0.10	1.50 ± 0.10	0.90 ± 0.10	8.00 ± 0.10
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05



Reel dimensions





Index	Α	В	С
Dimension (mm)	Ф178.0	Ф60.0	Ф 13.0

Taping Quantity:2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

(1) Products in N_2 gas sealed bag should be used in 6 months from the day of WALSIN outgoing inspection and 1 month after open, which can be confirmed the quality.



Storage environment condition.

Products should be storage in the warehouse on the following conditions.

■ Temperature :-10 to +40°C

Humidity : 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.